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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16684**

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**Issue Date:** 26-Aug-2011

**TITLE:** 06673-002/20558-001 SOIC 16L CSAM Removal

**PROPOSED FIRST SHIP DATE:** 26-Nov-2011

**AFFECTED CHANGE CATEGORY(S):** After assembly

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or <[Henry.Hernandez@onsemi.com](mailto:Henry.Hernandez@onsemi.com)>

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or <[Josephine.Guevarra@onsemi.com](mailto:Josephine.Guevarra@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

CSAM verification is performed prior to shipment of the lot to customers, applicable for device# 06673-002/20558-001 SOIC 16L Atp1, as part of committed actions in die top delamination improvement plans dating back to 1999. Subsequent process improvements have successfully eliminated the die delamination, rendering the CSAM verification no longer necessary."



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**RELIABILITY DATA SUMMARY:**

**2011 MRT GATE RESULTS**

Seq	Date IN	Device	AMKOR ID	ON ASSY ID	ON ID	REL ID	Date Code	QTY	EOL SAT	Post SAT	Result	MSL Level	Remarks
1	8-Mar-11	20558-001	107E3651	PSZR1070081	C22961.1	TX111010	1108LWG	22	0/18170	0/18170	passed	MSL 2	no die top delam
2	8-Mar-11	20558-001	108E3067	PSZR1080042	C23356.1	TX111020	1109LBR	22	0/13156	0/13156	passed	MSL 2	no die top delam
3	5-Apr-11	20558-001	108E3371	PSZR1080053	C23395.1	TX111201	1109LDS	22	0/15991	0/15991	passed	MSL2	no die top delam
4	13-Apr-11	20558-001	112E3461	PSZR1120073	C25226.1	TX111510	1113LYF	22	0/19411	0/19333	passed	MSL2	no die top delam
5	13-Apr-11	20558-001	112E3462	PSZR1120074	C25105.2	TX111520	1113LYK	22	0/1355	0/1364	passed	MSL2	no die top delam
6	12-May-11	20558-001	115E2058	PSZR1150026	C26279.1	TX111810	1116LLM	22	0/14847	0/14847	passed	MSL2	no die top delam
7	12-May-11	20558-001	115E1596	PSZR1140077	C26278.1	TX111820	1116LMC	22	0/19258	0/19258	passed	MSL2	no die top delam
8	12-May-11	20558-001	115E3005	PSZR1150046	C16464.1	TX111830	1117LOW	22	0/20481	0/19532	passed	MSL2	no die top delam
9	26-May-11	20558-001	118E1855	PSZR1180009		TX112110	1119LAV	22			passed	MSL2	no die top delam

**ELECTRICAL CHARACTERISTIC SUMMARY:** Not applicable

**List of affected Customer Specific Parts:**

MPN impact list (ASICs)	Affected Companies	Impacted BU's (PTI2)
06673-002-XTD	NAGANO KEIKI CO LTD	AA
20558-001-XTD	ON SEMICONDUCTOR	
	TEXAS INSTRUMENTS INC	